



Material Content Data Sheet



Sales Product Name		IDD03SG60C		Issued		29. August 2013		
MA#		MA000809442						
Package		PG-TO252-3-311		Weight*		311.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.032	0.01		101	
	non noble metal	tin	7440-31-5	0.008	0.00		26	
	inorganic material	silicon	7440-21-3	0.401	0.13	0.14	1288	1415
leadframe	non noble metal	iron	7439-89-6	0.162	0.05		521	
	inorganic material	phosphorus	7723-14-0	0.049	0.02		156	
	non noble metal	copper	7440-50-8	162.275	52.06	52.13	520539	521216
wire	non noble metal	aluminium	7429-90-5	0.126	0.04	0.04	403	403
encapsulation	organic material	carbon black	1333-86-4	1.449	0.46		4647	
	plastics	epoxy resin	-	25.351	8.13		81321	
	inorganic material	silicondioxide	60676-86-0	118.065	37.87	46.46	378723	464691
leadfinish	non noble metal	tin	7440-31-5	3.740	1.20	1.20	11997	11997
plating	non noble metal	nickel	7440-02-0	0.086	0.03		277	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	278
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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